



## Material Content Data Sheet



<b>Sales Product Name</b>		BSF030NE2LQ		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000961536							
<b>Package</b>		MG-WDSO-N-2-3		<b>Weight*</b>		49.30 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.664	3.37	3.37	33748	33748	
leadframe	non noble metal	copper	7440-50-8	45.114	91.52	91.52	915185	915185	
leadfinish	non noble metal	nickel	7440-02-0	0.115	0.23		2327		
	noble metal	silver	7440-22-4	0.456	0.93	1.16	9254	11581	
plating	non noble metal	nickel	7440-02-0	0.077	0.16	0.16	1571	1571	
glue	plastics	epoxy resin	-	0.103	0.21		2088		
	noble metal	silver	7440-22-4	0.632	1.28	1.49	12825	14913	
solder	non noble metal	copper	7440-50-8	0.005	0.01		106		
	noble metal	silver	7440-22-4	0.031	0.06		634		
	non noble metal	tin	7440-31-5	1.006	2.04	2.11	20404	21144	
passivation	plastics	epoxy resin	-	0.092	0.19	0.19	1858	1858	
*deviation	< 10%					Sum in total:	100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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